Surface Mount Ultrafast Power Rectifier

This SMA flat lead ultrafast rectifier provides fast switching performance with soft recovery in a compact thermally efficient package. Its compact footprint makes it ideally suited to portable and automotive applications where board space is at a premium. Its low profile makes it a good option for flat panel display and other applications with limited vertical clearance. The device offers low leakage over temperature making it a good match for applications requiring low quiescent current.

Features

- Fast Soft Switching for Reduced EMI and Higher Efficiency
- Low Profile Maximum Height of 1.1 mm
- Small Footprint Footprint Area of 13.5 mm²
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 95 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds
- MSL 1

Applications

- Switching Power Supplies including Mini-adapters and Displays
- Instrumentation
- Engine Control Recirculation Diodes
- Freewheeling Diode Where Space is at a Premium



ON Semiconductor®

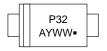
www.onsemi.com

ULTRAFAST RECTIFIER 3.0 AMPERE 200 VOLTS



SMA-FL CASE 403AA STYLE 6

MARKING DIAGRAM



P32 = Specific Device Code A = Assembly Location

Y = Year WW = Work Week ■ = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
NHPAF320T3G	SMA-FL (Pb-Free)	5000 / Tape & Reel
NRVHPAF320T3G	SMA-FL (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating		Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current (T _L = 115°C)	lo	3.0	А
Peak Repetitive Forward Current (Rated V _R , Square Wave, 20 kHz) T _L = 105°C	I _{FRM}	6.0	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	110	А
Storage Temperature Range	T _{stg}	-65 to +175	°C
Operating Junction Temperature	TJ	-65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1)	$\Psi_{\sf JCL}$	29	°C/W
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{ heta JA}$	80	°C/W

^{1. 1} inch square pad size (1 \times 0.5 inch) for each lead on FR4 board.

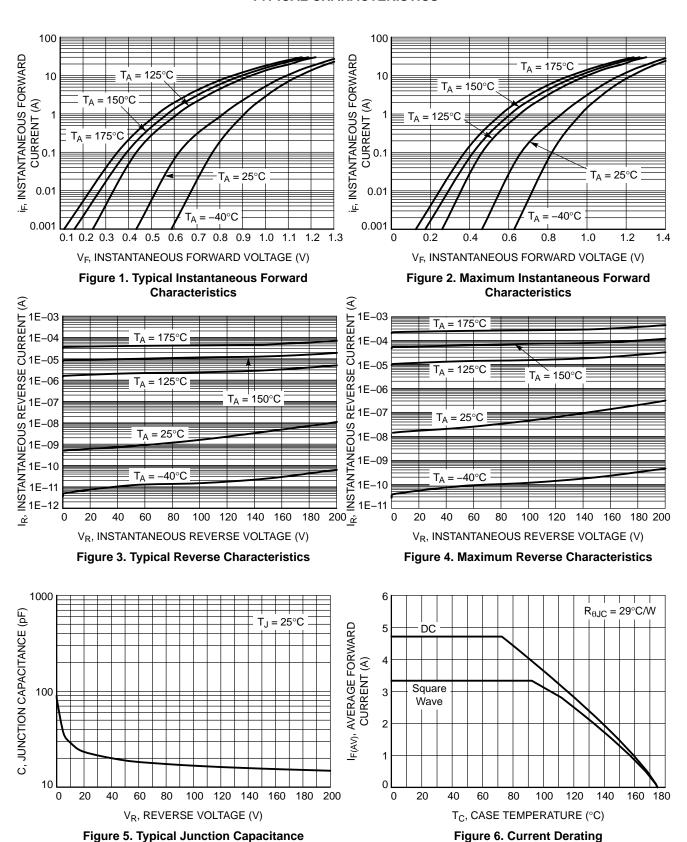
ELECTRICAL CHARACTERISTICS

		Value		
Characteristic	Symbol	T _J = 25°C	T _J = 125°C	Unit
Maximum Instantaneous Forward Voltage (Note 2) (i _F = 3.0 A)	VF	1.00	0.80	V
Maximum Instantaneous Reverse Current (Note 2) (V _R = 200 V)	I _R	0.50	25	μΑ
Reverse Recovery Time $I_F = 3.0 \text{ A}, V_R = 30 \text{ V}, \text{dl/dt} = 50 \text{ A/}\mu\text{s}, T_J = 25^{\circ}\text{C}$	t _{rr}	30		ns
Reverse Recovery Time $I_F = 3.0 \text{ A}, V_R = 30 \text{ V}, \text{ dl/dt} = 50 \text{ A/}\mu\text{s}, T_J = 125^{\circ}\text{C}$	t _{rr}	50		ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{2.} Pulse Test: Pulse Width \leq 380 μ s, Duty Cycle \leq 2.0%.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

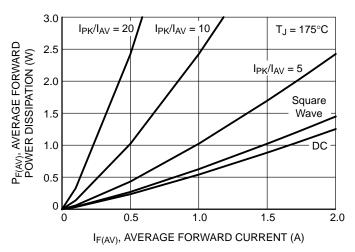


Figure 7. Forward Power Dissipation

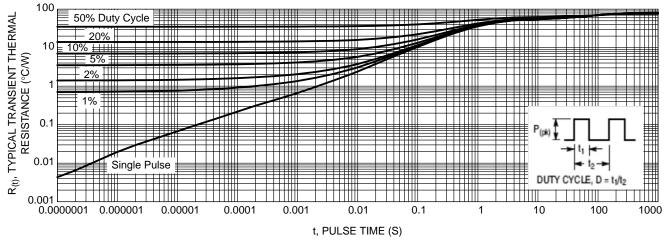


Figure 8. Typical Transient Thermal Response, Junction-to-Ambient





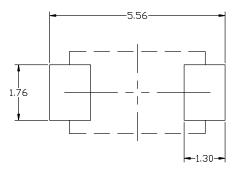
SMA 2.60x4.30x1.00 CASE 403AA ISSUE A

DATE 18 JAN 2024

NOTES:

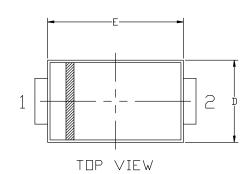
- DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. FL

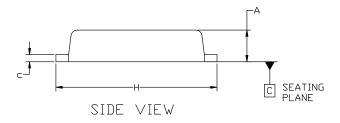
MILLIMETERS					
DIM	MIN	NDM	MAX		
Α	0.90	1.00	1.10		
b	1.25	1.45	1.65		
\subset	0.15	0.225	0.30		
D	2.40	2.60	2,80		
Ε	4.00	4.30	4.60		
Н	4.80	5.10	5.40		
L	0.70	0.90	1.10		

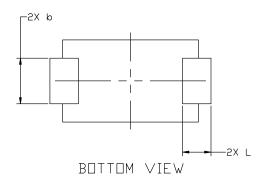


RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference manual, SDLDERRM/D.







GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

A = Assembly Location

Y = Year

WW = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON55210E	Electronic versions are uncontrolled except when accessed directly from the Document Reposito Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SMA 2.60x4.30x1.00		PAGE 1 OF 1	

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales